

**THERMAL MANAGEMENT WITH FILLED POLYMERIC POLISHING PADS AND
APPLICATIONS THEREFOR**

ABSTRACT OF THE DISCLOSURE

The present invention is directed, in general, to a method of planarizing a surface on a semiconductor wafer and, more specifically, to a method of altering the properties of polishing pads to improve thermal management during chemical-mechanical planarization, the resulting heat conductive pad and a polishing apparatus that includes the pad. The pad includes a polishing body composed of a thermoconductive polymer comprising an substrate and filler particle containing a Group II salt and within the substrate.